NLSF595

Serial (SPI) Tri-Color LED Driver

The NLSF595 is advanced CMOS shift register with open drain outputs fabricated with 0.6 μm silicon gate CMOS technology. This device is used in conjunction with a microcontroller, with only one dedicated line. All pins have Overvoltage Protection that allows voltages above V_{CC} up to 7.0 V to be present on the pins without damage or disruption of operation of the part, regardless of the operating voltage. This device may be used between 2.0 and 5.5 volts, the output driver level may be independent of supply voltage: 0–7.0 volts.

Features

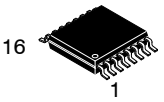
- Parallel Outputs are Open Drain Capable of Sinking > 12 mA
  - Output Withstands up to +7.0 Regardless of V_{CC}
- Standard Serial (SPI) Interface, Data, Clock, Enable (Low)
- All Inputs CMOS Level Compatible
- Frees up I/O around a Microcontroller
- Only One Pin Dedicated to this Device (Latch Enable)
- Output Enable may be Permanently Pulled Low
- High Speed Clocking, Fmax > 25 MHz (Shift Clock)
- Eight Bits Parallel Output
- Double Buffered Outputs, so Register may Fill without Affecting Output
- STD CMOS Serial Output, may be used to Cascade more than One Device
- Each Part Controls Two Tri–Color LEDs
- Two Devices can Control 5 Tri–Color LEDs
- Low Leakage: I_{CC} = 2.0 μA (Max) at T_A = 25°C
- Latchup Performance Exceeds 100 mA
- QFN–16/TSSOP–16 Packages
- ESD Performance:
  - Human Body Model; > 2000 V
  - Machine Model; > 200 V
- Functionally Similar to the Popular 74VHC595
- These Devices are Pb–Free and are RoHS Compliant

ON Semiconductor®

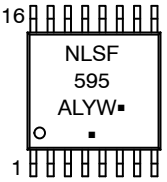
http://onsemi.com

MARKING DIAGRAMS

QFN–16
MN SUFFIX
CASE 485G



TSSOP–16
DT SUFFIX
CASE 948F



A	= Assembly Location
L	= Wafer Lot
Y	= Year
W	= Work Week
▪	= Pb–Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 12 of this data sheet.

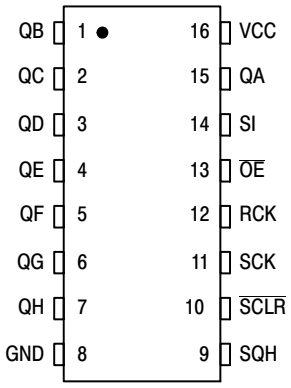


Figure 1. Pin Assignment (TSSOP−16)

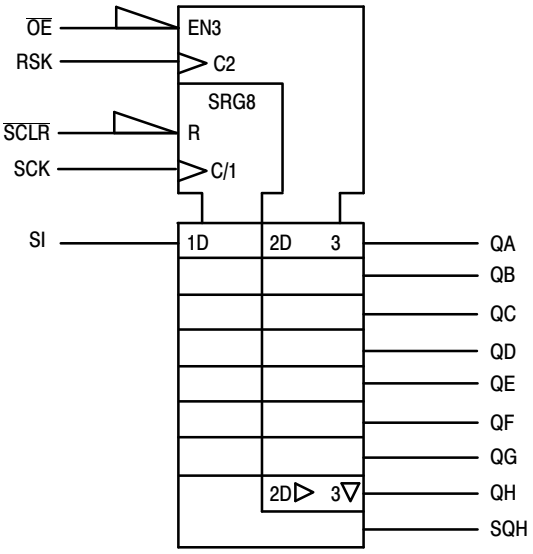


Figure 2. IEC Logic Symbol

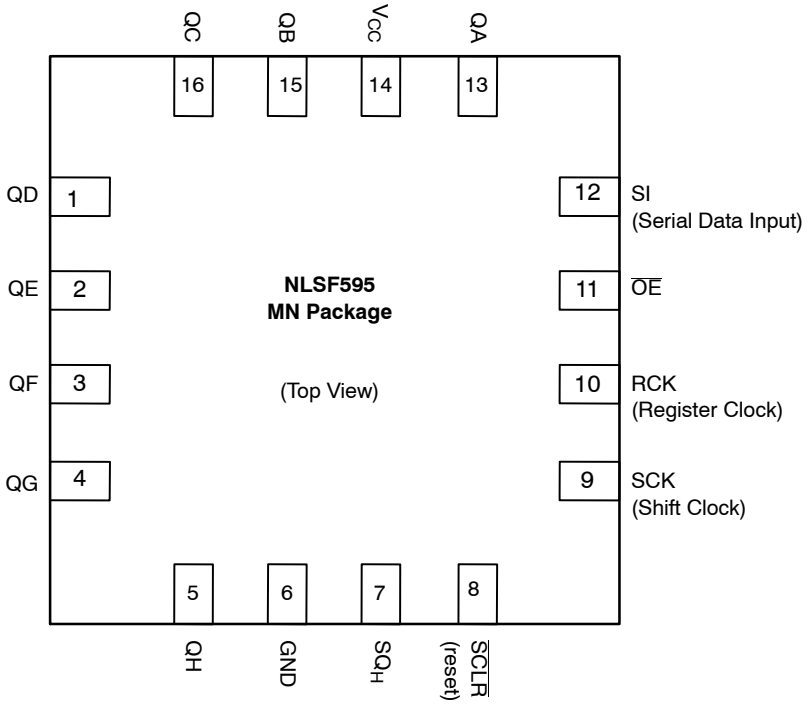


Figure 3. Pin Assignment (QFN−16)

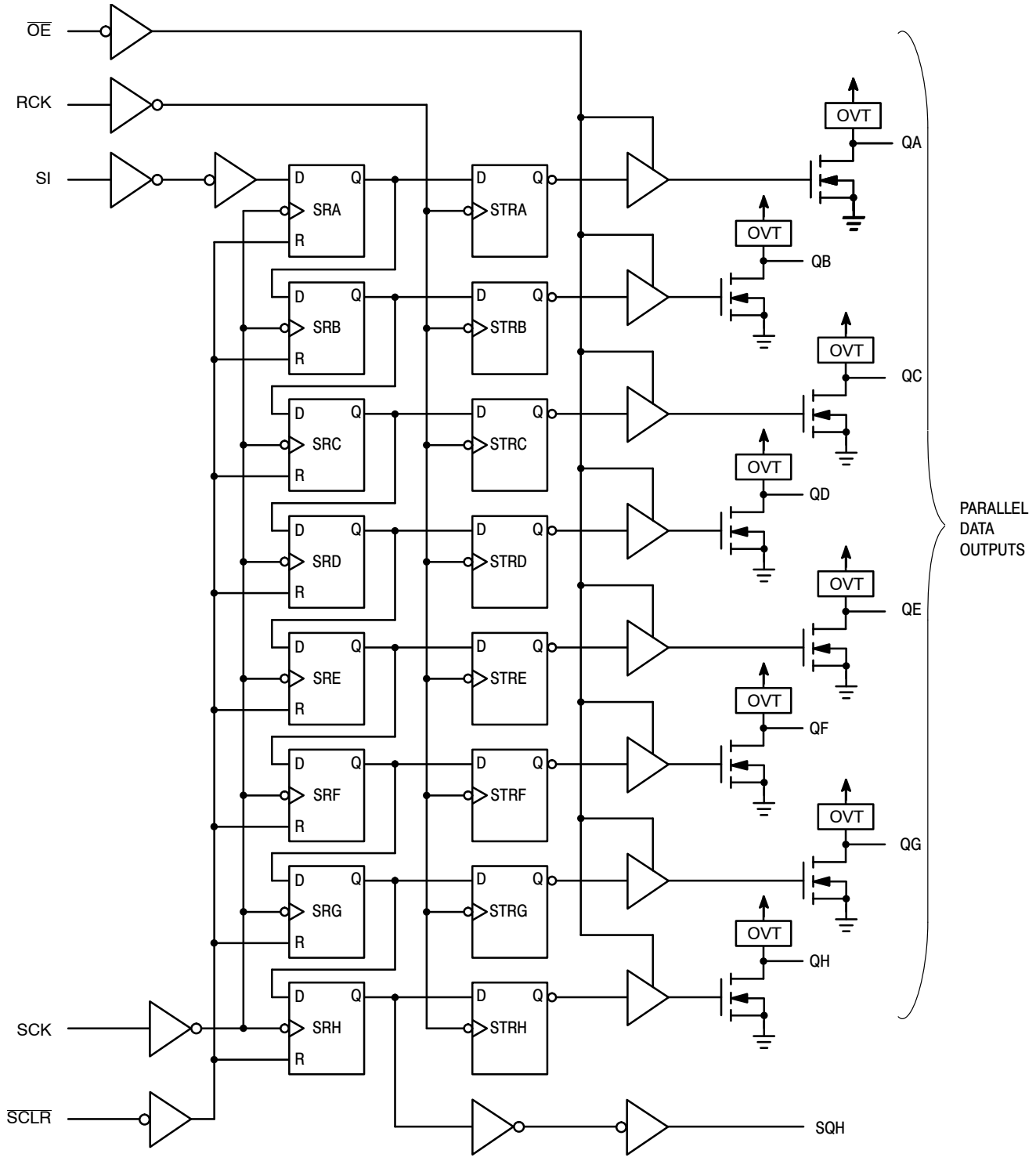


Figure 4. Expanded Logic Diagram

MAXIMUM RATINGS

Symbol	Parameter	Value	Units
V_{CC}	Positive DC Supply Voltage	−0.5 to +7.0	V
V_{IN}	Digital Input Voltage	−0.5 to +7.0	V
V_{OUT}	DC Output Voltage	−0.5 to V_{CC} +7.0	V
I_{IK}	Input Diode Current	−20	mA
I_{OK}	Output Diode Current	±50	mA
I_{OUT}	DC Output Current, per Pin	+50	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	±75	mA
P_D	Power Dissipation in Still Air	450	mW
T_{STG}	Storage Temperature Range	−65 to +150	°C
$I_{LATCHUP}$	Latchup Performance Above V_{CC} and Below GND at 125°C (Note 1)	±300	mA
θ_{JA}	Thermal Resistance, Junction−to−Ambient	128	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Tested to EIA/JESD78

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Units
V_{CC}	DC Supply Voltage	2.0	5.5	V
V_{IN}	DC Input Voltage	0	5.5	V
V_{OUT}	DC Output Voltage	0	V_{CC}	V
T_A	Operating Temperature Range, all Package Types	−55	125	°C
t_r, t_f	Input Rise or Fall Time V_{CC} = 3.3 V ± 0.3 V V_{CC} = 5.0 V ± 0.5 V	0	 50 15	ns/V

FUNCTION TABLE

	Inputs					Resulting Function			
Operation	Reset ($\overline{SCLR}$)	Serial Input (SI)	Shift Clock (SCK)	Reg Clock (RCK)	Output Enable ($\overline{OE}$)	Shift Register Contents	Storage Register Contents	Serial Output (SQH)	Parallel Outputs (QA – QH)
Clear shift register	L	X	X	L, H, ↓	L	L	U	L	U
Shift data into shift register	H	D	↑	L, H, ↓	L	$D \rightarrow SR_A$; $SR_N \rightarrow SR_{N+1}$	U	$SR_G \rightarrow SR_H$	U
Registers remains unchanged	H	X	L, H, ↓	X	L	U	**	U	**
Transfer shift register contents to storage register	H	X	L, H, ↓	↑	L	U	$SR_N \rightarrow STR_N$	*	SR_N
Storage register remains unchanged	X	X	X	L, H, ↓	L	*	U	*	U
Enable parallel outputs	X	X	X	X	L	*	**	*	Enabled
Force outputs into high impedance state	X	X	X	X	H	*	**	*	Z

SR = shift register contents
STR = storage register contents
D = data (L, H) logic level
U = remains unchanged
↓ = High−to−Low
↑ = Low−to−High
* = depends on Reset and Shift Clock inputs
** = depends on Register Clock input

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	V_{CC} (V)	T_A = 25°C			$T_A \le 85°C$		$T_A \le 125°C$		Units
				Min	Typ	Max	Min	Max	Min	Max	
V_{IH}	Minimum High−Level Input Voltage		2.0 3.0 4.5 5.5	1.5 2.1 3.15 3.85			1.5 2.1 3.15 3.85		1.5 2.1 3.15 3.85		V
V_{IL}	Maximum Low−Level Input Voltage		2.0 3.0 4.5 5.5			0.59 0.9 1.35 1.65		0.59 0.9 1.35 1.65		0.59 0.9 1.35 1.65	V
V_{OH}	Minimum High−Level Serial Output Only Output Voltage $V_{IN} = V_{IH}$ or V_{IL}	$V_{IN} = V_{IH}$ or V_{IL} I_{OH} = −50 μA	2.0 3.0 4.5	1.9 2.9 4.4	2.0 3.0 4.5		1.9 2.9 4.4		1.9 2.9 4.4		V
		$V_{IN} = V_{IH}$ or V_{IL} I_{OH} = −4 mA I_{OH} = −8 mA	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		
V_{OL}	Maximum Low−Level Output Voltage $V_{IN} = V_{IH}$ or V_{IL}	I_{OL} = 50 μA	2.0 3.0 4.5		0.0 0.0 0.0	0.1 0.1 0.1		0.1 0.1 0.1		0.1 0.1 0.1	V
		I_{OL} = 4 mA I_{OL} = 8 mA	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
V_{OL2}	Maximum Low−Level Output Voltage with Max. Load $V_{IN} = V_{IH}$ or V_{IL}	I_{OL} = 20 mA I_{OL} = 25 mA	3.0 4.5		0.8 0.5	1.0 0.6		1.1 0.7		1.25 0.8	V
I_{IN}	Maximum Input Leakage Current	V_{IN} = 5.5 V or GND	0 to 5.5			±0.1		±1.0		±1.0	μA
I_{CC}	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			4.0		40.0		40.0	μA
I_{OZ}	Three−State Output Off−State Current QA−QH	$V_{IN} = V_{IH}$ or V_{IL} $V_{OUT} = V_{CC}$ or GND	5.5			±0.25		±2.5		±2.5	μA
I_{LKG}	Active (2) State Off Output Leakage Current QA−QH	$V_{IN} = V_{IH}$ or V_{IL} $V_{OUT} = V_{CC}$ or GND	5.5			±0.25		±2.5		±2.5	μA
I_{OFF}	Power Off Output Leakage All Outputs	V_{IN} = 0 or 5.5 V V_{OUT} = 5.5 V	0			±0.25		±2.5		±2.5	μA

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 3.0$ ns)

Symbol	Parameter	Test Conditions	$T_A = 25°C$ Min	$T_A = 25°C$ Typ	$T_A = 25°C$ Max	$T_A \le 85°C$ Min	$T_A \le 85°C$ Max	$T_A \le 125°C$ Min	$T_A \le 125°C$ Max	Units
f_{max}	Maximum Clock Frequency (50% Duty Cycle)	$V_{CC} = 3.3 \pm 0.3$ V	80	150		70		70		MHz
		$V_{CC} = 5.0 \pm 0.5$ V	135	185		115		115		
t_{PLH}, t_{PHL}	Propagation Delay, SCK to SQH	$V_{CC} = 3.3 \pm 0.3$ V $C_L = 15$ pF		8.8	13.0	1.0	15.0	1.0	15.0	ns
		$C_L = 50$ pF		11.3	16.5	1.0	18.5	1.0	18.5	
		$V_{CC} = 5.0 \pm 0.5$ V $C_L = 15$ pF		6.2	8.2	1.0	9.4	1.0	9.4	
		$C_L = 50$ pF		7.7	10.2	1.0	11.4	1.0	11.4	
t_{PHL}	Propagation Delay, $\overline{SCLR}$ to SQH	$V_{CC} = 3.3 \pm 0.3$ V $C_L = 15$ pF		8.4	12.8	1.0	13.7	1.0	13.7	ns
		$C_L = 50$ pF		10.9	16.3	1.0	17.2	1.0	17.2	
		$V_{CC} = 5.0 \pm 0.5$ V $C_L = 15$ pF		5.9	8.0	1.0	9.1	1.0	9.1	
		$C_L = 50$ pF		7.4	10.0	1.0	11.1	1.0	11.1	
t_{PLZ}	Output Disable Time RCK to QA−QH	$V_{CC} = 3.3 \pm 0.3$ V $C_L = 15$ pF		7.7	11.9	1.0	13.5	1.0	13.5	ns
		$C_L = 50$ pF		10.2	15.4	1.0	17.0	1.0	17.0	
	Output Enable Time RCK to QA−QH	$V_{CC} = 5.0 \pm 0.5$ V $C_L = 15$ pF		5.4	7.4	1.0	8.5	1.0	8.5	
		$C_L = 50$ pF		6.9	9.4	1.0	10.5	1.0	10.5	
t_{PZL}	Output Disable Time RCK to QA−QH	$V_{CC} = 3.3 \pm 0.3$ V $C_L = 15$ pF		7.7	11.9	1.0	13.5	1.0	13.5	ns
		$C_L = 50$ pF		10.2	15.4	1.0	17.0	1.0	17.0	
	Output Enable Time RCK to QA−QH	$V_{CC} = 5.0 \pm 0.5$ V $C_L = 15$ pF		5.4	7.4	1.0	8.5	1.0	8.5	
		$C_L = 50$ pF		6.9	9.4	1.0	10.5	1.0	10.5	
t_{PZL}	Output Enable Time, $\overline{OE}$ to QA−QH	$V_{CC} = 3.3 \pm 0.3$ V $C_L = 15$ pF $R_L = 1$ kΩ		7.5	11.5	1.0	13.5	1.0	13.5	ns
		$C_L = 50$ pF		9.0	15.0	1.0	17.0	1.0	17.0	
		$V_{CC} = 5.0 \pm 0.5$ V $C_L = 15$ pF $R_L = 1$ kΩ		4.8	8.6	1.0	10.0	1.0	10.0	
		$C_L = 50$ pF		8.3	10.6	1.0	12.0	1.0	12.0	
t_{PLZ}	Output Disable Time, $\overline{OE}$ to QA−QH	$V_{CC} = 3.3 \pm 0.3$ V $C_L = 50$ pF $R_L = 1$ kΩ		12.1	15.7	1.0	16.2	1.0	16.2	ns
		$V_{CC} = 5.0 \pm 0.5$ V $C_L = 50$ pF $R_L = 1$ kΩ		7.6	10.3	1.0	11.0	1.0	11.0	
C_{IN}	Input Capacitance			4	10		10		10	pF
C_{OUT}	Three−State Output Capacitance (Output in High−Impedance State), QA−QH			6			10		10	pF

		Typical @ 25°C, $V_{CC} = 5.0$ V	
C_{PD}	Power Dissipation Capacitance (Note 2)	87	pF

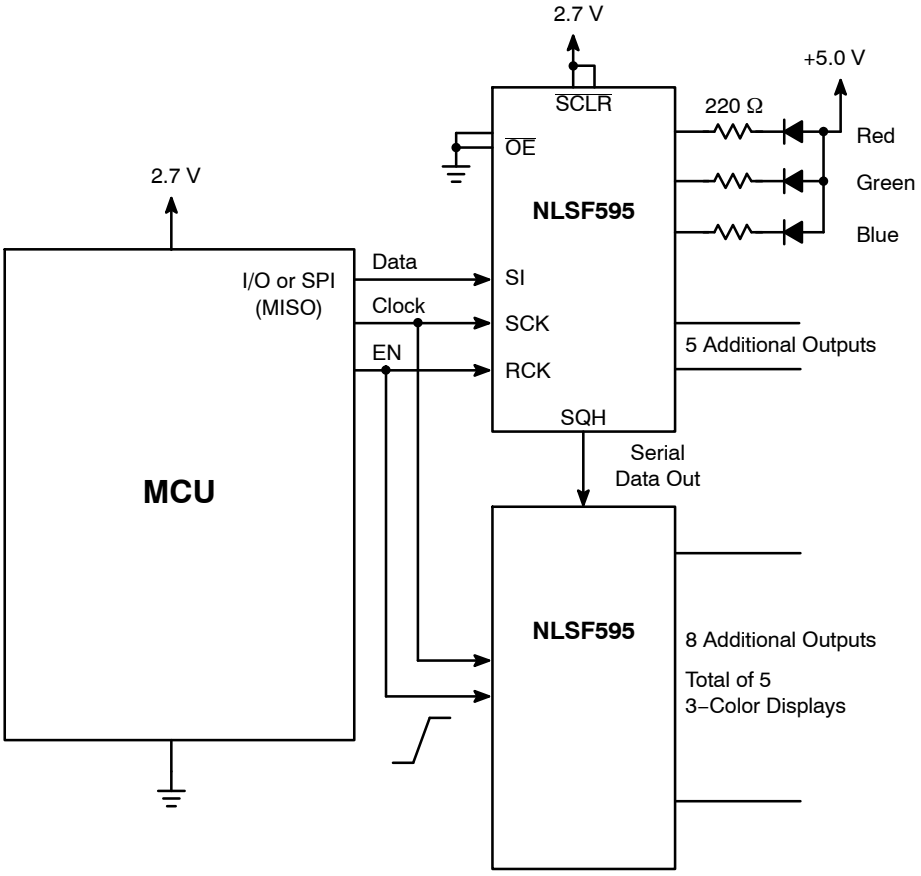
2. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no−load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

NOISE CHARACTERISTICS (Input $t_r = t_f = 3.0$ ns, $C_L = 50$ pF, $V_{CC} = 5.0$ V)

Symbol	Characteristic	$T_A = 25°C$ Typ	$T_A = 25°C$ Max	Units
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}	0.8	1.0	V
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}	−0.8	−1.0	V
V_{IHD}	Minimum High Level Dynamic Input Voltage		3.5	V
V_{ILD}	Maximum Low Level Dynamic Input Voltage		1.5	V

TIMING REQUIREMENTS (Input $t_r = t_f = 3.0$ns)

Symbol	Parameter	V_{CC} V	T_A = 25°C		T_A = − 40 to 85°C	T_A = − 55 to 125°C	Units
			Typ	Limit	Limit	Limit	
t_{su}	Setup Time, SI to SCK	3.3 5.0		3.5 3.0	3.5 3.0	3.5 3.0	ns
$t_{su(H)}$	Setup Time, SCK to RCK	3.3 5.0		8.0 5.0	8.5 5.0	8.5 5.0	ns
$t_{su(L)}$	Setup Time, $\overline{SCLR}$ to RCK	3.3 5.0		8.0 5.0	9.0 5.0	9.0 5.0	ns
t_h	Hold Time, SI to SCK	3.3 5.0		1.5 2.0	1.5 2.0	1.5 2.0	ns
$t_{h(L)}$	Hold Time, $\overline{SCLR}$ to RCK	3.3 5.0		0 0	0 0	1.0 1.0	ns
t_{rec}	Recovery Time, $\overline{SCLR}$ to SCK	3.3 5.0		3.0 2.5	3.0 2.5	3.0 2.5	ns
t_w	Pulse Width, SCK or RCK	3.3 5.0		5.0 5.0	5.0 5.0	5.0 5.0	ns
$t_{w(L)}$	Pulse Width, $\overline{SCLR}$	3.3 5.0		5.0 5.0	5.0 5.0	5.0 5.0	ns



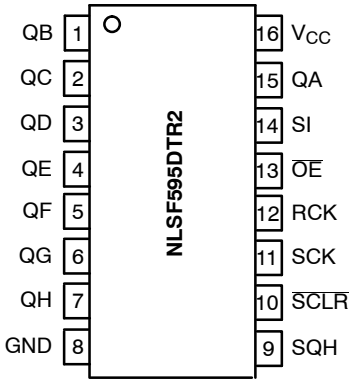


Figure 5. NLSF595 Shown Driving 5 3−Color LEDs

SWITCHING WAVEFORMS

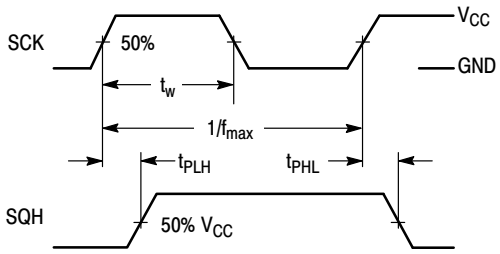


Figure 6.

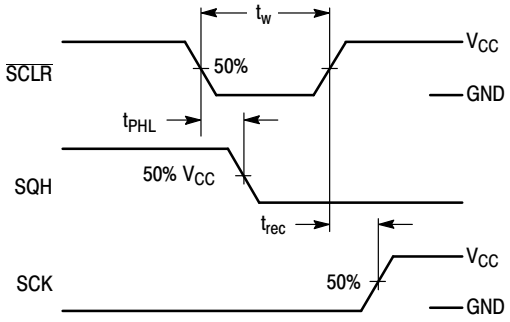


Figure 7.

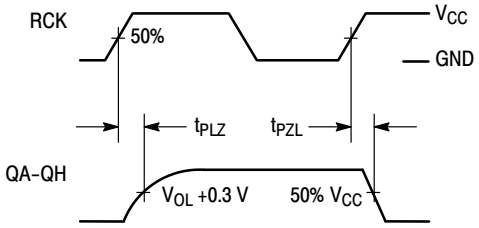


Figure 8.

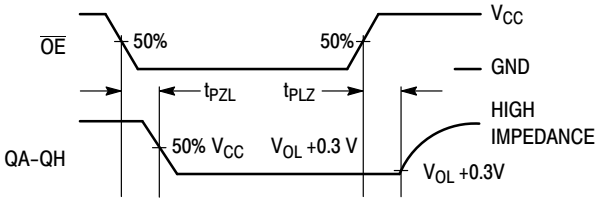


Figure 9.

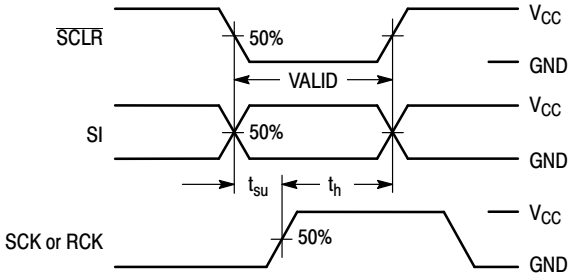


Figure 10.

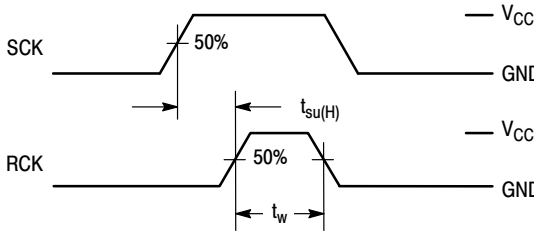
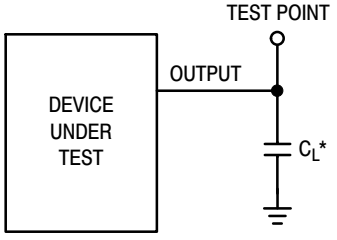


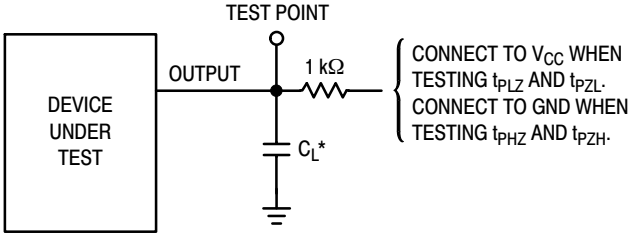
Figure 11.

TEST CIRCUITS



*Includes all probe and jig capacitance

Figure 12.



*Includes all probe and jig capacitance

Figure 13.

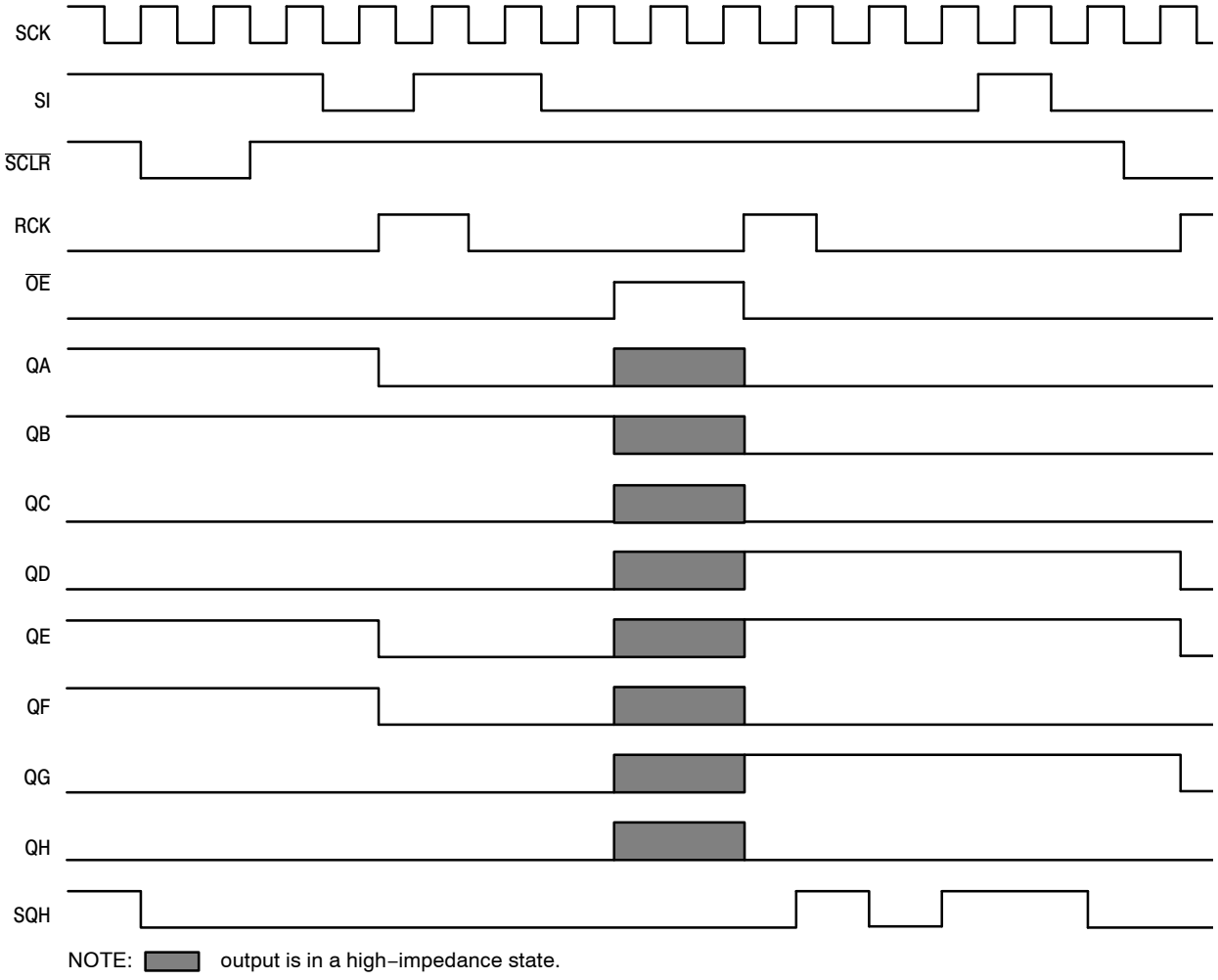


Figure 14. Timing Diagram

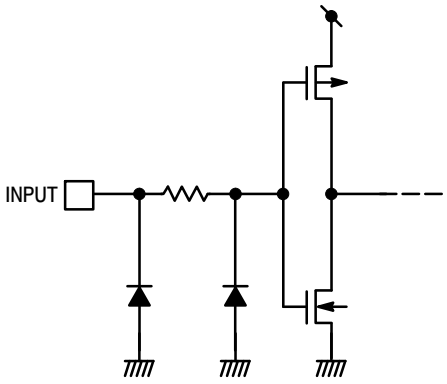


Figure 15. Input Equivalent Circuit

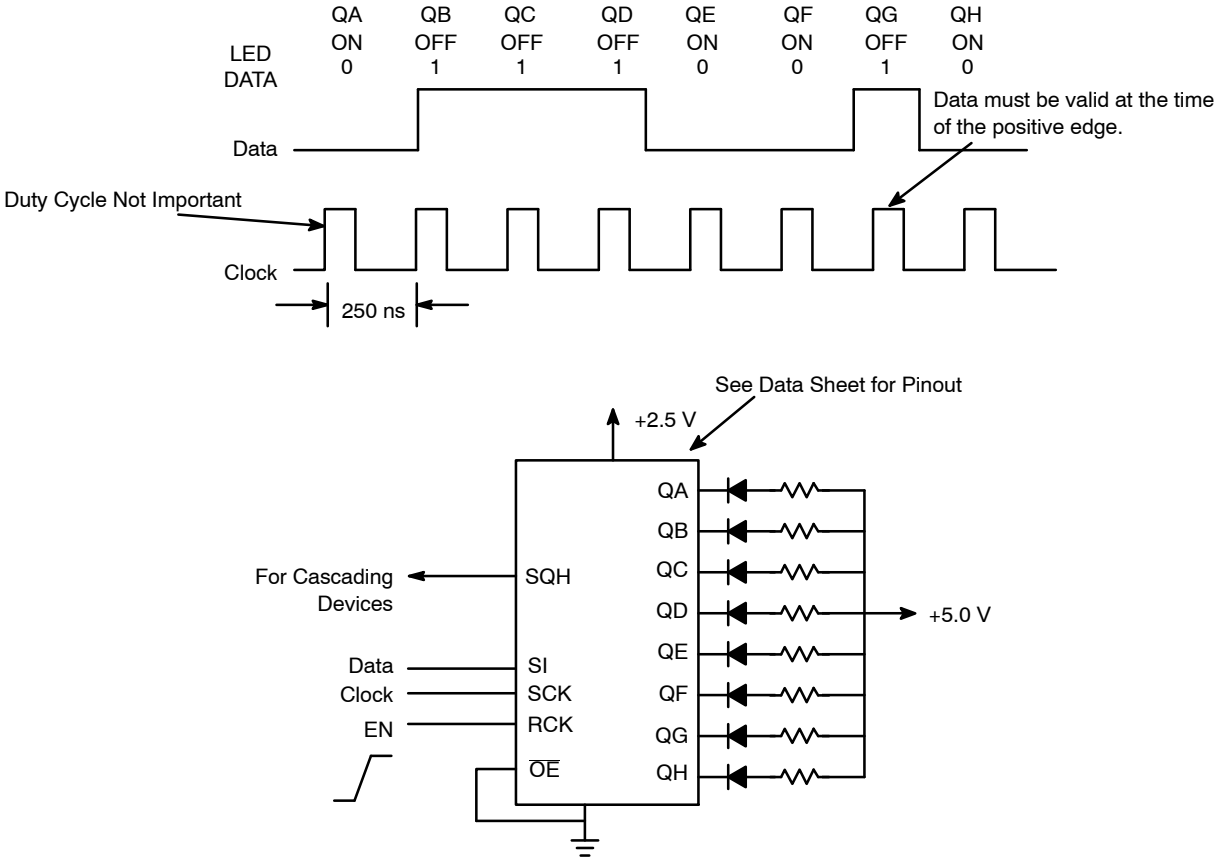


Figure 16. NLSF595 Example

ORDERING INFORMATION

Device Order Number	Device Nomenclature					Package	Shipping†
	Circuit Indicator	Technology	Device Function	Package Suffix	Tape & Reel Suffix		
NLSF595MNR2G	NL	SF	595	MN	R2	QFN (Pb−Free)	13−inch/3000 Unit
NLSF595DTR2G	NL	SF	595	DT	R2	TSSOP* (Pb−Free)	13−inch/2500 Unit

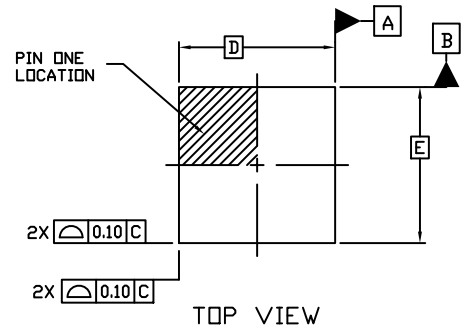
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb−Free.

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

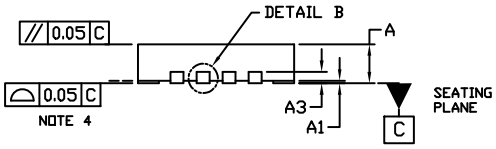
QFN16 3x3, 0.5P
CASE 485G
ISSUE G

DATE 08 OCT 2021

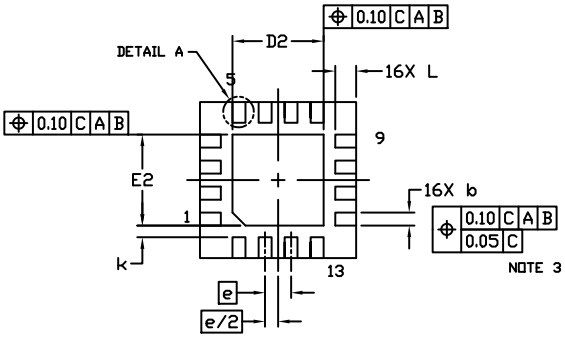
SCALE 2:1



TOP VIEW

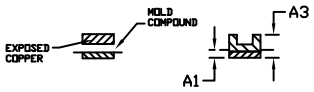


SIDE VIEW

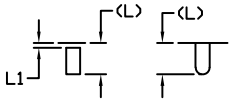


BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.



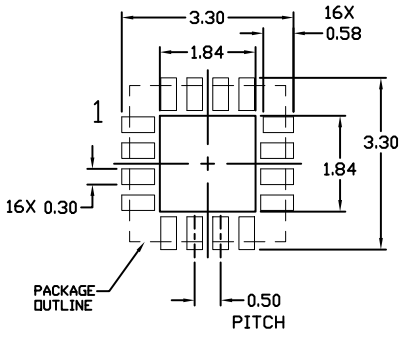
DETAIL B
ALTERNATE CONSTRUCTIONS



DETAIL A
ALTERNATE TERMINAL CONSTRUCTIONS

	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.03	0.05
A3		0.20 REF	
b	0.18	0.24	0.30
D		3.00 BSC	
D2	1.65	1.75	1.85
E		3.00 BSC	
E2	1.65	1.75	1.85
e		0.50 BSC	
k		0.18 TYP	
L	0.30	0.40	0.50
L1	0.00	0.08	0.15

MOUNTING FOOTPRINT



GENERIC MARKING DIAGRAM*

XXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

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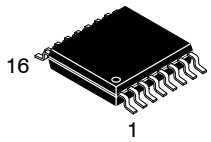
DESCRIPTION:	**QFN16 3X3, 0.5P**	**PAGE 1 OF 1**

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

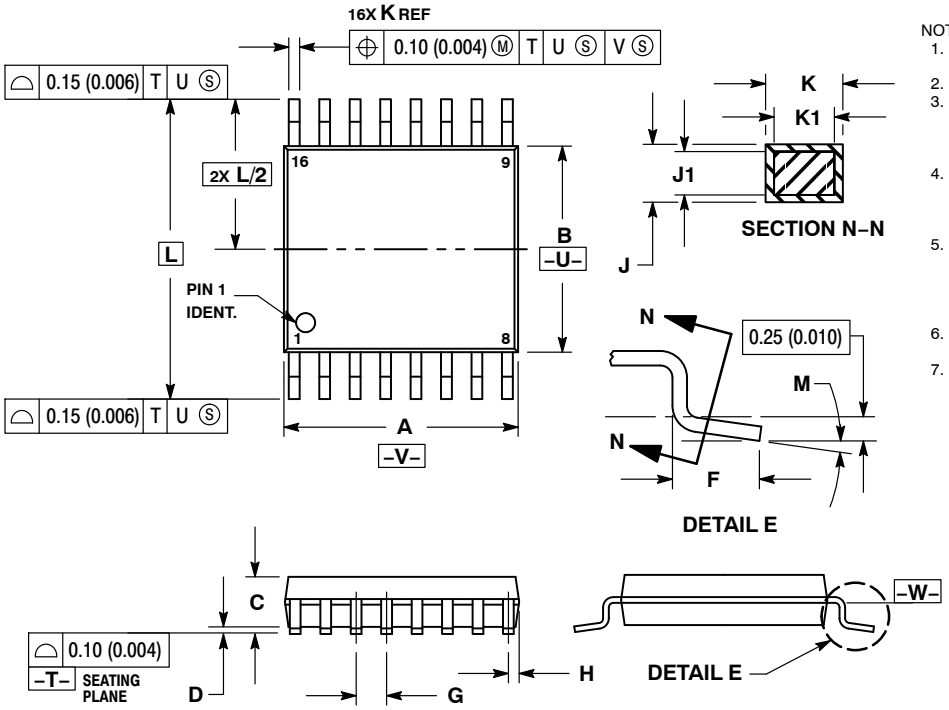
ON Semiconductor®



SCALE 2:1

TSSOP−16
CASE 948F−01
ISSUE B

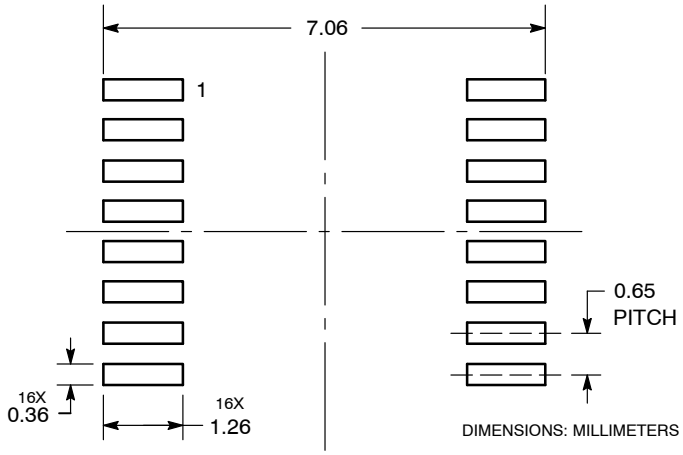
DATE 19 OCT 2006



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

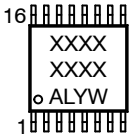
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	−−−	1.20	−−−	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0 °	8 °	0 °	8 °

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

GENERIC MARKING DIAGRAM*



XXXX	= Specific Device Code
A	= Assembly Location
L	= Wafer Lot
Y	= Year
W	= Work Week
G or ▪	= Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

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